

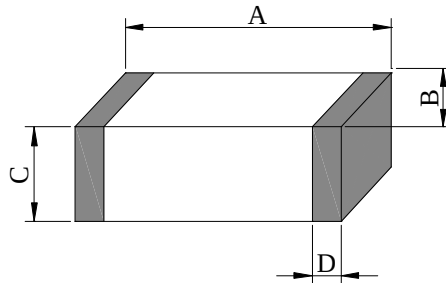
SPECIFICATION FOR APPROVAL

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PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MH1005□□□□2□-□□□
		ABC'S ITEM NO.	

I . CONFIGURATION & DIMENSIONS :



A : 1.00±0.10 m/m

B : 0.50±0.10 m/m

C : 0.50±0.10 m/m

D : 0.23±0.10 m/m

II . SCHEMATIC DIAGRAM :



III . FEATURES :

- a . Monolithic structure ensuring high performance and reliability.
- b . High frequency applications up to 6GHz.
- c . Terminal : Ag/Cu/Ni/Sn
- d . Remark : Products comply with RoHS' requirements

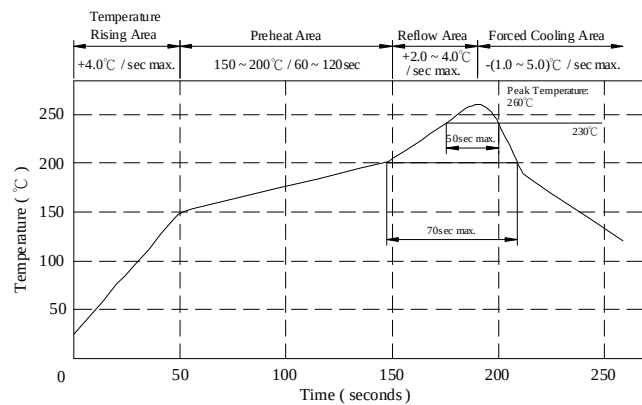
IV . APPLICATIONS :

- a . RF modules for telecommunication systems including GSM, PCS, DECT, WLAN, Bluetooth, etc.

V . GENERAL SPECIFICATION :

- a . Storage temp. : -55°C ---- +125°C
- b . Operating temp. : -55°C ---- +125°C
- c . Solderability : Preheat 150°C. 60 sec
Solder : H63A
Solder temp. : 230±5°C
Flux : Rosin
Dip time : 4±1 sec

Peak Temp : 260°C max.
Max time above 230°C : 50sec max.
Max time above 200°C : 70sec max.



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VI . ELECTRICAL CHARACTERISTICS :

DWG No.	Inductance (nH)	Q min	L / Q Test Freq. (MHz)	SRF (GHz) min	RDC (Ω) max	IDC (mA) max
MH10051N0D2□-□□□	1.0 ± 0.3	8	100	10.00	0.08	300
MH10051N2D2□-□□□	1.2 ± 0.3	8	100	10.00	0.09	300
MH10051N5D2□-□□□	1.5 ± 0.3	8	100	6.00	0.10	300
MH10051N8D2□-□□□	1.8 ± 0.3	8	100	6.00	0.12	300
MH10052N0D2□-□□□	2.0 ± 0.3	8	100	6.00	0.12	300
MH10052N2D2□-□□□	2.2 ± 0.3	8	100	6.00	0.13	300
MH10052N4D2□-□□□	2.4 ± 0.3	8	100	6.00	0.13	300
MH10052N7D2□-□□□	2.7 ± 0.3	8	100	6.00	0.13	300
MH10053N0D2□-□□□	3.0 ± 0.3	8	100	6.00	0.16	300
MH10053N3D2□-□□□	3.3 ± 0.3	8	100	6.00	0.16	300
MH10053N6D2□-□□□	3.6 ± 0.3	8	100	5.00	0.20	300
MH10053N9D2□-□□□	3.9 ± 0.3	8	100	4.00	0.21	300
MH10054N3D2□-□□□	4.3 ± 0.3	8	100	4.00	0.21	300
MH10054N7D2□-□□□	4.7 ± 0.3	8	100	4.00	0.21	300
MH10055N1D2□-□□□	5.1 ± 0.3	8	100	4.00	0.21	300
MH10055N6D2□-□□□	5.6 ± 0.3	8	100	4.00	0.23	300
MH10056N2D2□-□□□	6.2 ± 0.3	8	100	3.90	0.25	300
MH10056N8J2□-□□□	6.8 ± 5%	8	100	3.90	0.25	300
MH10057N5J2□-□□□	7.5 ± 5%	8	100	3.70	0.25	300
MH10058N2J2□-□□□	8.2 ± 5%	8	100	3.60	0.28	300
MH10059N1J2□-□□□	9.1 ± 5%	8	100	3.40	0.30	300
MH100510NJ2□-□□□	10.0 ± 5%	8	100	3.20	0.31	300
MH100512NJ2□-□□□	12.0 ± 5%	8	100	2.70	0.40	300
MH100515NJ2□-□□□	15.0 ± 5%	8	100	2.30	0.46	300
MH100518NJ2□-□□□	18.0 ± 5%	8	100	2.10	0.55	300
MH100522NJ2□-□□□	22.0 ± 5%	8	100	1.90	0.60	300
MH100527NJ2□-□□□	27.0 ± 5%	8	100	1.60	0.70	300
MH100533NJ2□-□□□	33.0 ± 5%	8	100	1.30	0.80	200
MH100539NJ2□-□□□	39.0 ± 5%	8	100	1.20	0.90	200
MH100547NJ2□-□□□	47.0 ± 5%	8	100	1.00	1.00	200
MH100556NJ2□-□□□	56.0 ± 5%	8	100	0.75	1.00	200
MH100568NJ2□-□□□	68.0 ± 5%	8	100	0.75	1.20	180
MH100582NJ2□-□□□	82.0 ± 5%	8	100	0.60	1.30	150
MH1005R10J2□-□□□	100.0 ± 5%	8	100	0.60	1.50	150
MH1005R12J2□-□□□	120.0 ± 5%	8	100	0.60	1.60	150

1). □ : Packaging Information... ☐A : Bulk ☐B : Taping Reel

2). "-□□□" : Reference code

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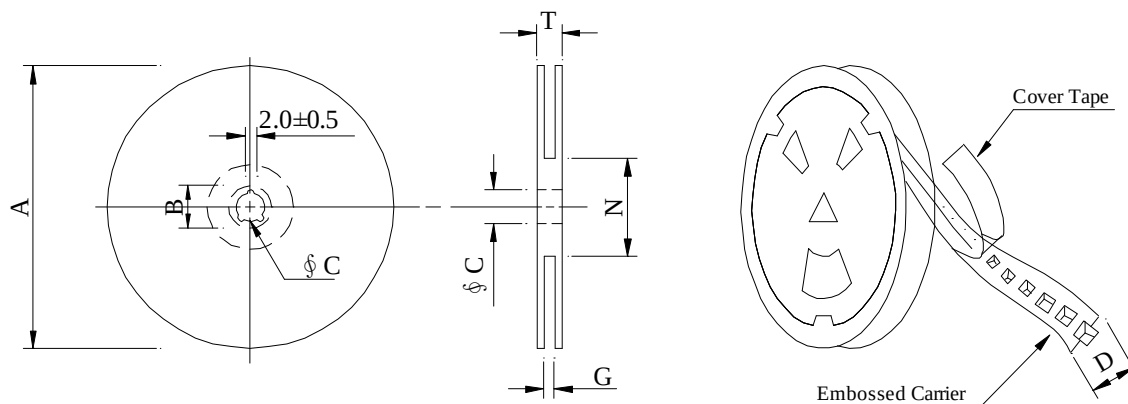
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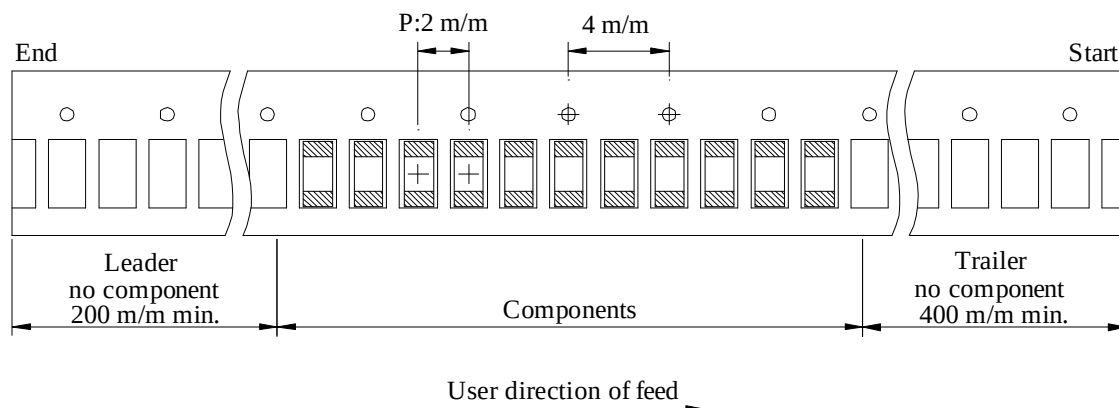
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VII . PACKAGING INFORMATION :

(1) Configuration



※ Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (kpcs)	G.W. (Kg)	Size (cm)
MH1005	10,000	60	07 - 08	500	5.5	42 x 41 x 24

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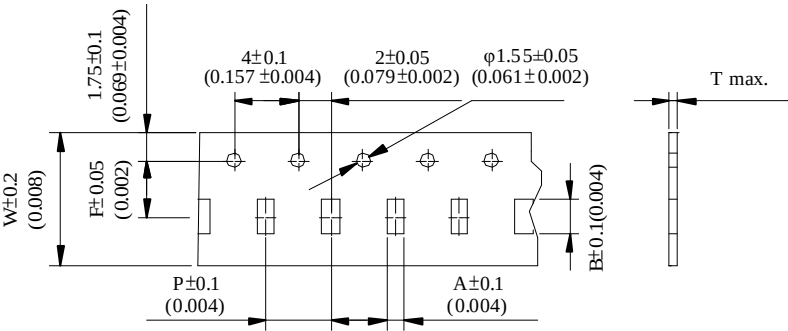
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(4) TYPE DIMENSIONS

Fig 1.



Unit:m/m

Type	A	B	F	P	T	W	Fig
MH1005	0.65	1.15	3.50	2.0	0.80	8.0	1

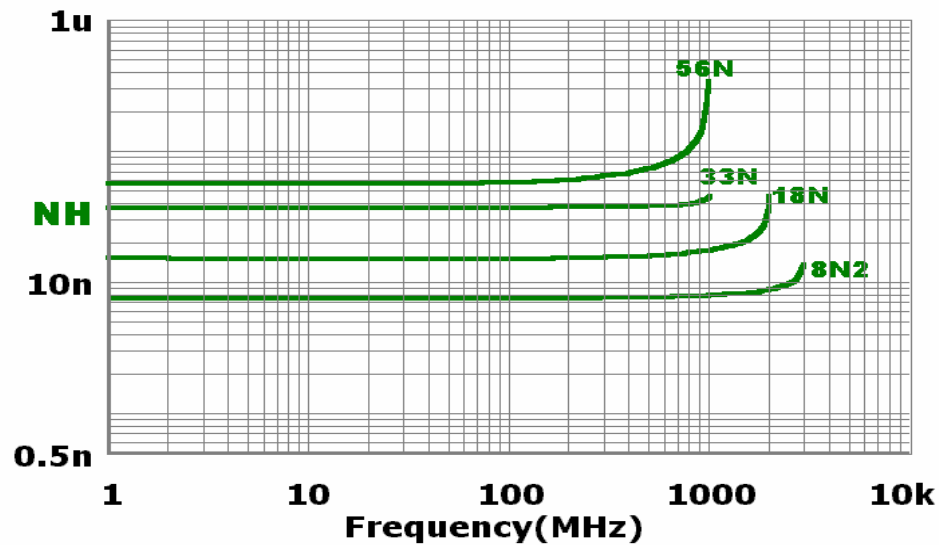
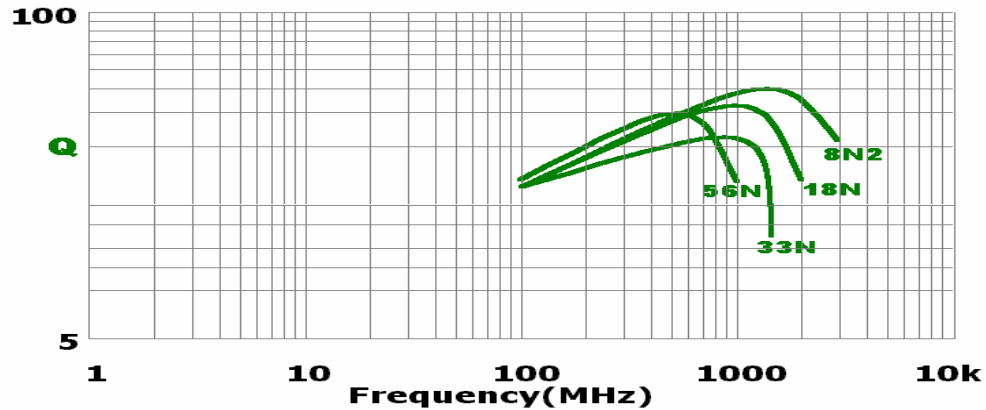
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VIII . L / Q VS. FREQ. CURVE :



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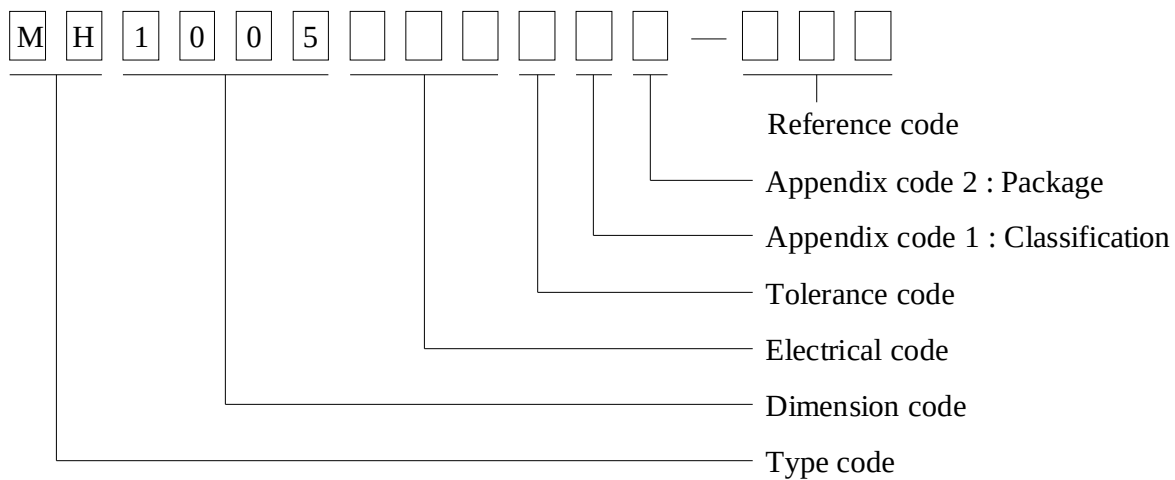
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IX . DWGING NUMBER EXPRESSION :



Appendix code 1 : Product Classification

L : Lead Free Standard products comply with RoHS' requirements

1 ~ 9 : Lead Free Special products comply with RoHS' requirements

Appendix code 2 : Package Information

Code	Inner package	Inner package Q'TY	Remark
A	T.B.D.	T.B.D.	
B	T / R (Reel package)	10000 pcs	

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